

FEATURES

- Member of the Texas Instruments Widebus™ Family
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

This 12-bit to 24-bit bus exchanger is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16271 is intended for applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. This device is particularly suitable as an interface between conventional DRAMs and high-speed microprocessors.

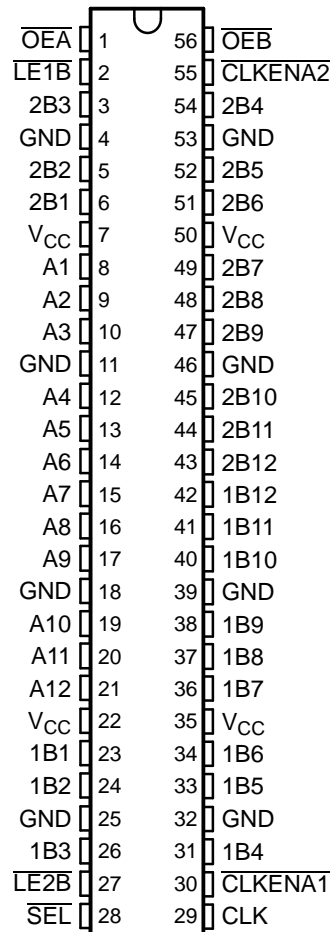
A data is stored in the internal A-to-B registers on the low-to-high transition of the clock (CLK) input, provided that the clock-enable (\overline{CLKENA}) inputs are low. Proper control of these inputs allows two sequential 12-bit words to be presented as a 24-bit word on the B port.

Transparent latches in the B-to-A path allow asynchronous operation to maximize memory access throughput. These latches transfer data when the latch-enable (\overline{LE}) inputs are low. The select (\overline{SEL}) line selects 1B or 2B data for the A outputs. Data flow is controlled by the active-low output enables (\overline{OEA} , \overline{OEB}).

To ensure the high-impedance state during power up or power down, the output enables should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

DGG OR DL PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tube	SN74ALVCH16271DL	ALVCH16271
		Tape and reel	SN74ALVCH16271DLR	
	TSSOP - DGG	Tape and reel	SN74ALVCH16271DGGR	ALVCH16271

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

SN74ALVCH16271
12-BIT TO 24-BIT MULTIPLEXED BUS EXCHANGER
WITH 3-STATE OUTPUTS

SCES017G—JULY 1995—REVISED SEPTEMBER 2004

FUNCTION TABLES

OUTPUT ENABLE

INPUTS		OUTPUTS	
$\overline{OE\bar{A}}$	$\overline{OE\bar{B}}$	A	1B, 2B
H	H	Z	Z
H	L	Z	Active
L	H	Active	Z
L	L	Active	Active

A-TO-B STORAGE ($\overline{OE\bar{B}} = L$)

INPUTS				OUTPUTS	
$\overline{CLKENA1}$	$\overline{CLKENA2}$	CLK	A	1B	2B
H	H	X	X	1B ₀ ⁽¹⁾	2B ₀ ⁽¹⁾
L	X	↑	L	L	X
L	X	↑	H	H	X
X	L	↑	L	X	L
X	L	↑	H	A ₀	H

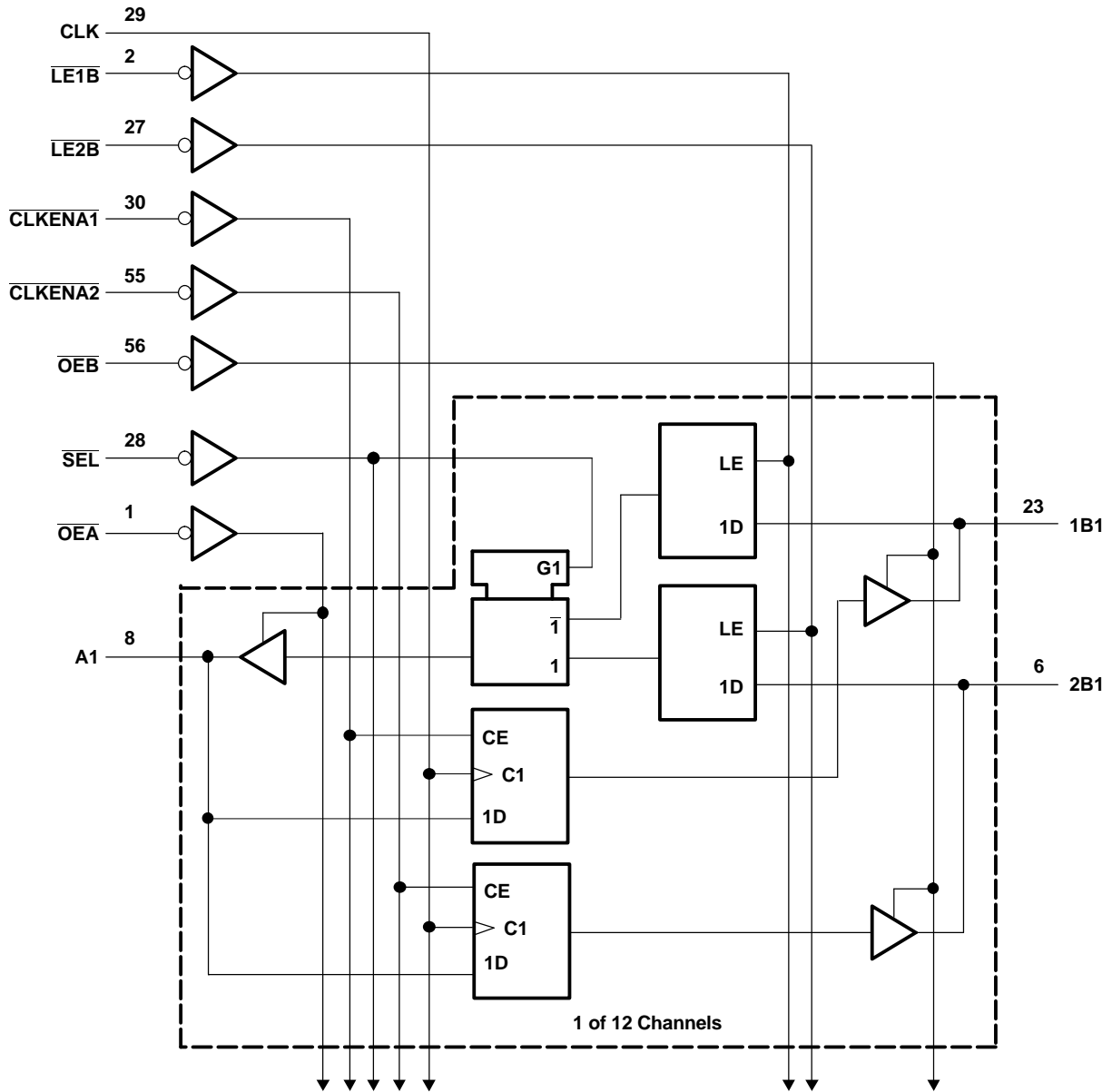
(1) Output level before the indicated steady-state input conditions were established

B-TO-A STORAGE ($\overline{OE\bar{A}} = L$)

INPUTS				OUTPUT A
\overline{LE}	\overline{SEL}	1B	2B	
H	X	X	X	A ₀ ⁽¹⁾
H	X	X	X	A ₀ ⁽¹⁾
L	H	L	X	L
L	H	H	X	H
L	L	X	L	L
L	L	X	H	H

(1) Output level before the indicated steady-state input conditions were established

LOGIC DIAGRAM (POSITIVE LOGIC)



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	4.6	V
V _I	Input voltage range	Except I/O ports ⁽²⁾		V
		I/O ports ⁽²⁾⁽³⁾		
V _O	Output voltage range ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50 mA
I _{OK}	Output clamp current	V _O < 0		-50 mA
I _O	Continuous output current			±50 mA
	Continuous current through each V _{CC} or GND			±100 mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	DGG package		64 °C/W
		DL package		56
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V		V
		V _{CC} = 2.3 V to 2.7 V		
		V _{CC} = 2.7 V to 3.6 V		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V		V
		V _{CC} = 2.3 V to 2.7 V		
		V _{CC} = 2.7 V to 3.6 V		
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V		mA
		V _{CC} = 2.3 V		
		V _{CC} = 2.7 V		
		V _{CC} = 3 V		
I _{OL}	Low-level output current	V _{CC} = 1.65 V		mA
		V _{CC} = 2.3 V		
		V _{CC} = 2.7 V		
		V _{CC} = 3 V		
Δt/Δv	Input transition rise or fall rate			10 ns/V
T _A	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			V
	I _{OH} = -4 mA	1.65 V	1.2			
	I _{OH} = -6 mA	2.3 V	2			
	I _{OH} = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I _{OH} = -24 mA	3 V	2				
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
	I _{OL} = 4 mA	1.65 V			0.45	
	I _{OL} = 6 mA	2.3 V			0.4	
	I _{OL} = 12 mA	2.3 V			0.7	
		2.7 V			0.4	
	I _{OL} = 24 mA	3 V			0.55	
I _I	V _I = V _{CC} or GND	3.6 V			±5	μA
I _{I(hold)}	V _I = 0.58 V	1.65 V	25			μA
	V _I = 1.07 V	1.65 V	-25			
	V _I = 0.7 V	2.3 V	45			
	V _I = 1.7 V	2.3 V	-45			
	V _I = 0.8 V	3 V	75			
	V _I = 2 V	3 V	-75			
	V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ} ⁽³⁾	V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V			40	μA
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs V _I = V _{CC} or GND	3.3 V		3.5		pF
C _{io}	A or B ports V _O = V _{CC} or GND	3.3 V		9		pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	130		130		130		MHz
t _w	Pulse duration, CLK high or low	3.3		3.3		3.3		ns
t _{su}	Setup time	A before CLK↑	2.6	2.1	1.7			ns
		B before $\overline{\text{LE}}$	1.7	1.5	1.3			
		$\overline{\text{CLKEN}}$ before CLK↑	1.6	1.3	1			
t _h	Hold time	A after CLK↑	0.6	0.6	0.7			ns
		B after $\overline{\text{LE}}$	0.9	0.9	1.1			
		$\overline{\text{CLKEN}}$ after CLK↑	1	0.9	0.9			

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}				130		130		130		MHz
t _{pd}	CLK	B	8	1	6.2	5	1	4.3	ns	
	B	A	7	1	5.3	4.7	1.4	4		
	\overline{LE}		7	1	6	5.9	1.4	4.8		
	\overline{SEL}		7	1.1	6.4	6.2	1.3	5.2		
t _{en}	$\overline{OE}B$ or $\overline{OE}A$	B or A	8	1	6	6.1	1	5.1	ns	
t _{dis}	$\overline{OE}B$ or $\overline{OE}A$	B or A	7	1.4	5.4	4.6	1.7	4.2	ns	

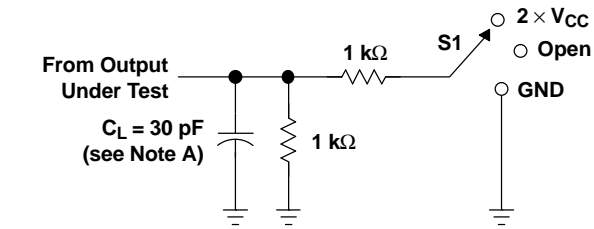
OPERATING CHARACTERISTICS

T_A = 25°C

PARAMETER			TEST CONDITIONS	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
				TYP	TYP	
C _{pd}	Power dissipation capacitance	A to B	Outputs enabled	92	105	pF
			Outputs disabled	61	76	
		B to A	Outputs enabled	39	43	
			Outputs disabled	11	13	

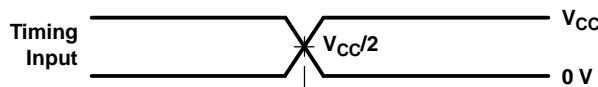
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 1.8\text{ V}$

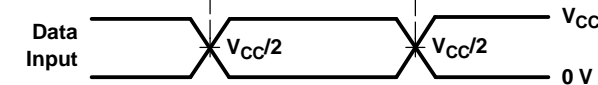


LOAD CIRCUIT

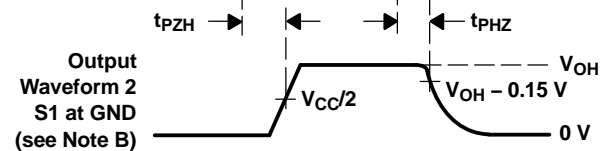
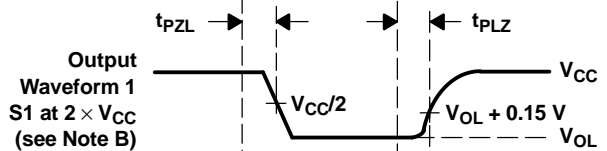
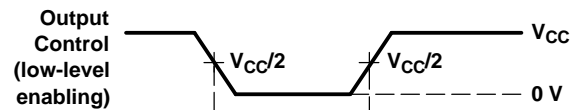
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 \times V_{CC}
t_{PHZ}/t_{PZH}	GND



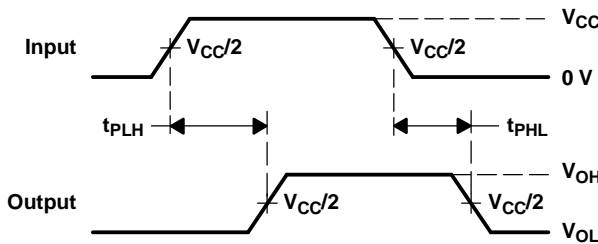
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES



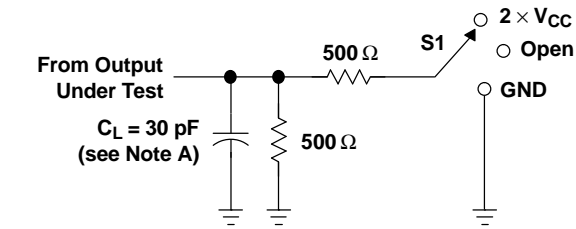
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

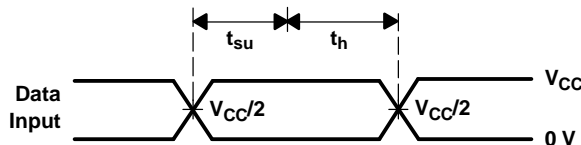
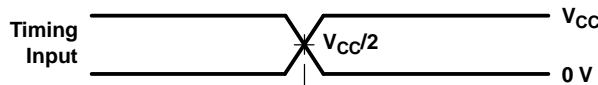
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5 V \pm 0.2 V$

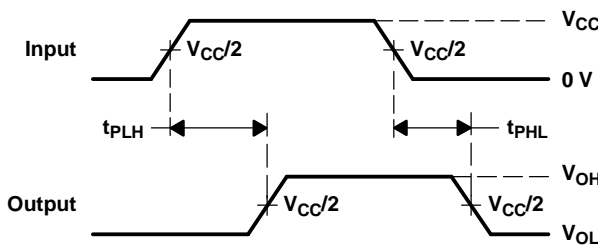


LOAD CIRCUIT

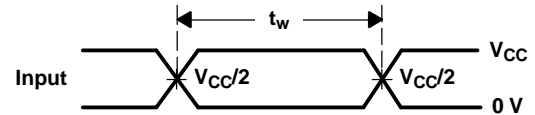
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



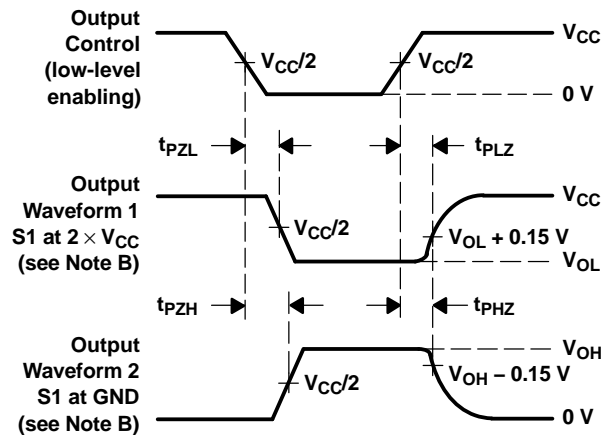
VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
 PULSE DURATION



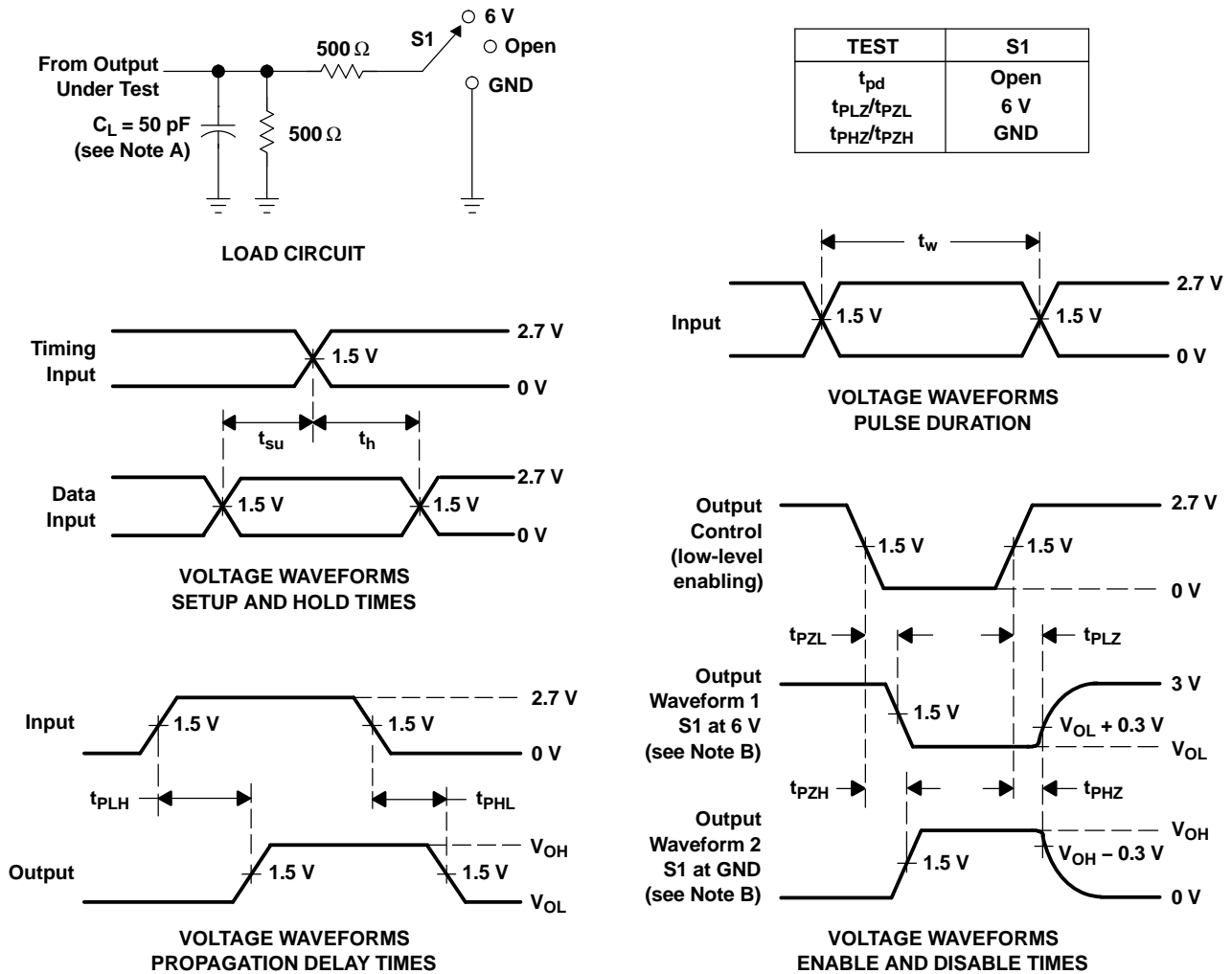
VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V}$ AND $3.3\text{ V} \pm 0.3\text{ V}$



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
74ALVCH16271DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74ALVCH16271DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALVCH16271DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16271DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16271DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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